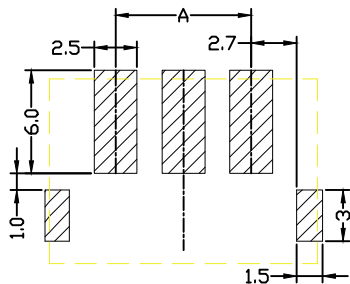
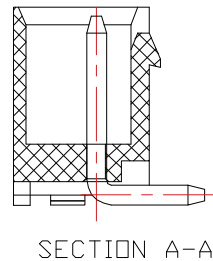
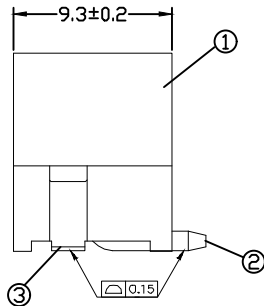
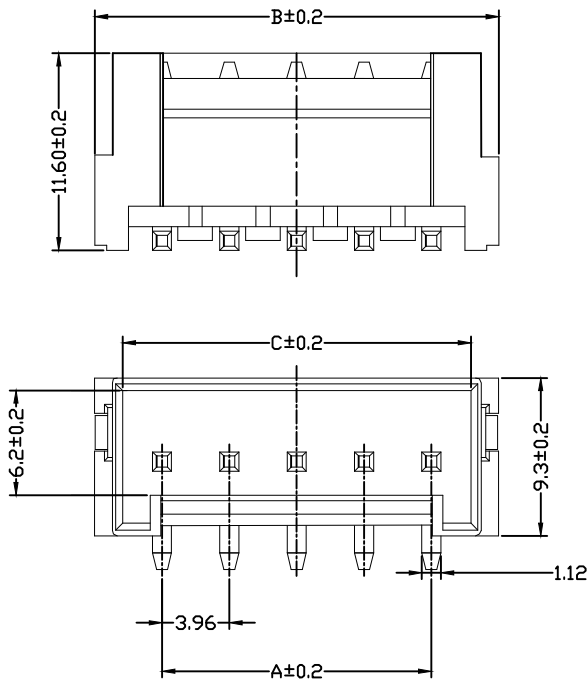
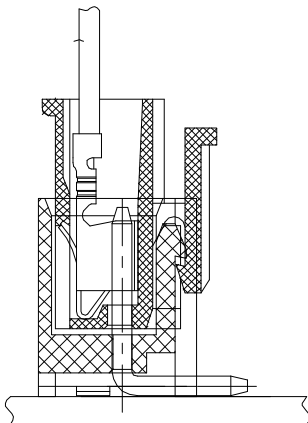


REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

- 技术要求:
- 1、塑件材料: LCP (UL-94V-0)
 - 2、接触件: 黄铜镀锡
 - 3、接触电阻: $\leq 30\text{m}\Omega$
 - 4、绝缘电阻: $\geq 1000\text{M}\Omega$
 - 5、额定电压: 250V AC DC
 - 6、额定电流: 7.0A AC DC
 - 7、耐压: 能承受1000V AC/Min ute
 - 8、工作温度: $-25^{\circ}\sim +85^{\circ}$
 - 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度260,时间 2.5 ± 0.5 秒
 - 10、铅和镉等六大有害物质含量要符合环保要求

Pin	A	B	C
2	3.96	11.88	8.6
3	7.92	15.84	12.56
4	11.88	19.8	16.52
5	15.84	23.76	20.48
6	19.8	27.72	24.44
7	23.76	31.68	28.4
8	27.72	35.64	32.36
9	31.68	39.6	36.32
10	35.64	43.56	40.28

3	垫片 Fitting Nail	黄铜	2	电镀(锡): 至少表面镀层30u"MIN, 再镀锡 80u"MIN.
2	端子 Contact	黄铜	n×1	电镀(锡): 至少表面镀层30u"MIN, 再镀锡 80u"MIN.
1	基板 Wafer	LCP (UL94V-0)	1	材料
序号	名称	材料	数量	附注

DESIGN:		Xiping Huang			广东国连电子有限公司			
CHECK:		Ke Tian			GUANGDONG GUOLIAN ELECTRONICS CO.,LTD			
APPROVED:		Youquan Xu			TITLE:			
DIM	TOL	DIM	TOL	3.96立贴				
X.	±0.25			PART NO.				
X.X	±0.20	X°	±3.0°	VH3.96-NAB				
X.XX	±0.15	X.X°		REV. A	SCALE: N/A	UNIT: mm	SHEET: 1/1	
X.XXX		X.XX°						
		X.XXX°						